

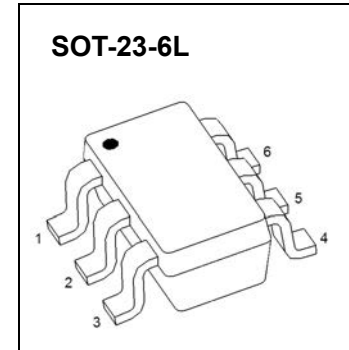
CB2321F P-channel and N-channel Complementary MOSFETS

N-channel

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
20V	60mΩ@4.5V	2.1A
	115mΩ@2.5V	

P-channel

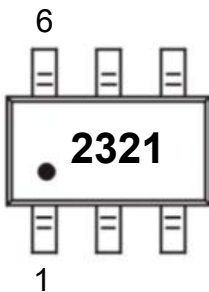
$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
-20V	112mΩ@-4.5V	-2.3A
	142mΩ@-2.5V	



GENERAL DESCRIPTION

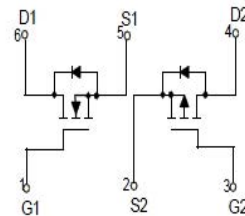
The CB2321F uses advanced trench technology to provide excellent $R_{DS(on)}$ and low gate charge. The complementary MOSFETS form a high-speed power inverter and suitable for a multitude of applications.

MARKING



2321=Device code
Solid point=Pin1 positioning point

Equivalent Circuit



Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value		Unit
		N-channel	P-channel	
Drain-Source Voltage	V_{DS}	20	-20	V
Gate-Source Voltage	V_{GS}	± 8	± 8	V
Continuous Drain Current	I_D	2.1	-2.3	A
Pulsed Drain Current (note 1)	I_{DM}	10	-10	A
Power Dissipation(note 2)	P_D	0.35		W
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	357		$^\circ\text{C}/\text{W}$
Operation Junction and Storage Temperature Range	T_J, T_{stg}	-55~+150		$^\circ\text{C}$

MOSFET ELECTRICAL CHARACTERISTICS

N-ch MOSFET ELECTRICAL CHARACTERISTICS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Static						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 10\mu A$	20			V
Gate-threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.60	0.95	1.2	
Gate-body leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 8V$			± 100	nA
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 20V, V_{GS} = 0V$			1	μA
Drain-source on-resistance ^a	$r_{DS(on)}$	$V_{GS} = 4.5V, I_D = 3.6A$		0.045	0.060	Ω
		$V_{GS} = 2.5V, I_D = 3.1A$		0.070	0.115	
Forward transconductance ^a	g_{fs}	$V_{DS} = 5V, I_D = 3.6A$		8		S
Diode forward voltage	V_{SD}	$I_S = 0.94A, V_{GS} = 0V$		0.76	1.2	V
Dynamic						
Total gate charge	Q_g	$V_{DS} = 10V, V_{GS} = 4.5V, I_D = 3.6A$		4.0	10	nC
Gate-source charge	Q_{gs}			0.65		
Gate-drain charge	Q_{gd}			1.5		
Input capacitance ^b	C_{iss}	$V_{DS} = 10V, V_{GS} = 0V, f = 1MHz$		300		pF
Output capacitance ^b	C_{oss}			120		
Reverse transfer capacitance ^b	C_{rss}			80		
Switching^b						
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 10V,$ $R_L = 5.5\Omega, I_D \approx 3.6A,$ $V_{GEN} = 4.5V, R_g = 6\Omega$		7	15	ns
Rise time	t_r			55	80	
Turn-off delay time	$t_{d(off)}$			16	60	
Fall time	t_f			10	25	

Notes :

- Pulse Test : Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- These parameters have no way to verify.

MOSFET ELECTRICAL CHARACTERISTICS

P-ch MOSFET ELECTRICAL CHARACTERISTICS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Static						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-20			V
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-0.4		-1	
Gate-source leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 8V$			± 100	nA
Zero gate voltage drain current	I_{DSS}	$V_{DS} = -16V, V_{GS} = 0V$			-1	μA
Drain-source on-state resistance ^a	$R_{DS(on)}$	$V_{GS} = -4.5V, I_D = -2.8A$		0.090	0.112	Ω
		$V_{GS} = -2.5V, I_D = -2.0A$		0.110	0.142	
Forward transconductance ^a	g_{fs}	$V_{DS} = -5V, I_D = -2.8A$		6.5		S
Dynamic^b						
Input capacitance	C_{iss}	$V_{DS} = -10V, V_{GS} = 0V, f = 1MHz$		405		pF
Output capacitance	C_{oss}			75		
Reverse transfer capacitance	C_{rss}			55		
Total gate charge	Q_g	$V_{DS} = -10V, V_{GS} = -4.5V, I_D = -3A$		5.5	10	nC
		$V_{DS} = -10V, V_{GS} = -2.5V, I_D = -3A$		3.3	6	
Gate-source charge	Q_{gs}	$V_{DS} = -10V, V_{GS} = -2.5V, I_D = -3A$		0.7		
Gate-drain charge	Q_{gd}			1.3		
Gate resistance	R_g	$f = 1MHz$		6.0		Ω
Turn-on delay time	$t_{d(on)}$	$V_{DD} = -10V,$ $R_L = 10\Omega, I_D = -1A,$ $V_{GEN} = -4.5V, R_g = 1\Omega$		11	20	ns
Rise time	t_r			35	60	
Turn-off delay time	$t_{d(off)}$			30	50	
Fall time	t_f			10	20	
Drain-source body diode characteristics						
Continuous source-drain diode current	I_S	$T_C = 25^\circ\text{C}$			-1.3	A
Pulse diode forward current ^a	I_{SM}				-10	
Body diode voltage	V_{SD}	$I_S = -0.7A$		-0.8	-1.2	V

Notes :

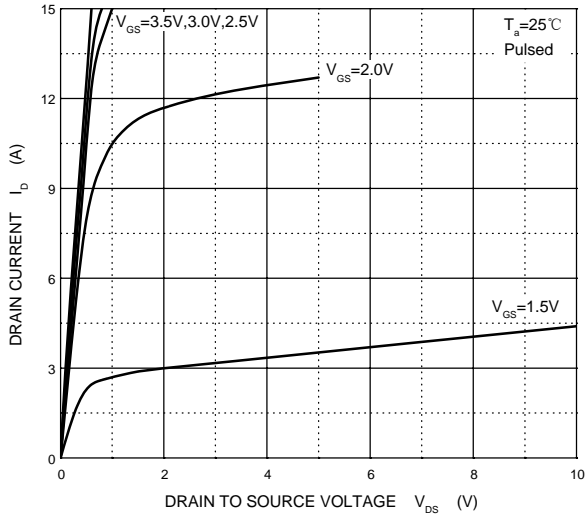
a. Pulse Test : Pulse Width < 300 μ s, Duty Cycle \leq 2%.

b. Guaranteed by design, not subject to production testing.

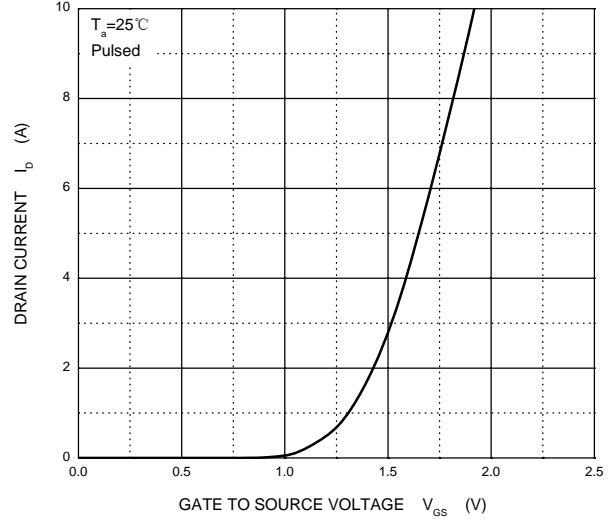
Typical Characteristics

N-Channel MOS

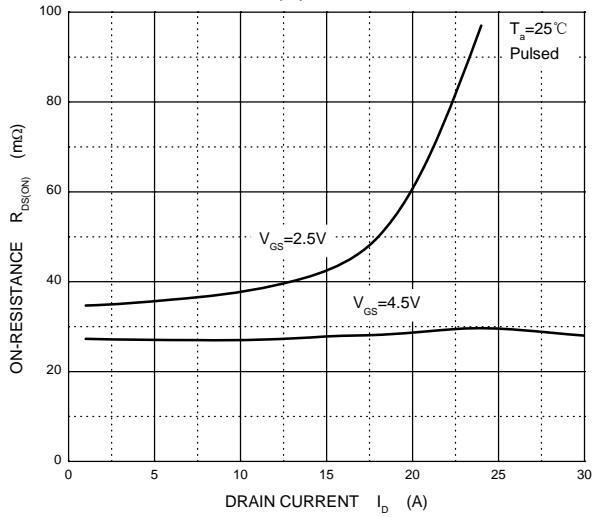
Output Characteristics



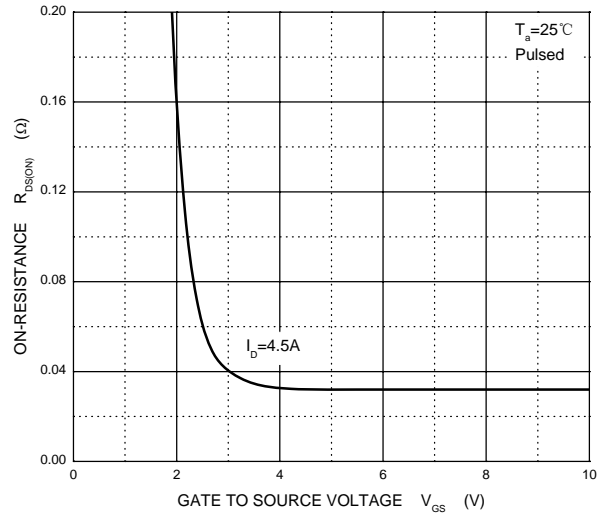
Transfer Characteristics



$R_{DS(ON)}$ — I_D

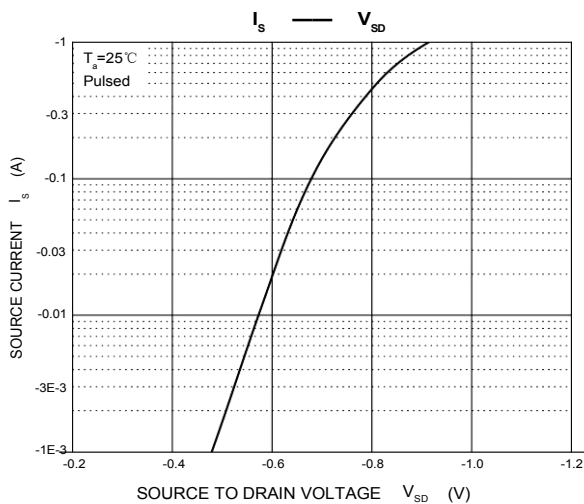
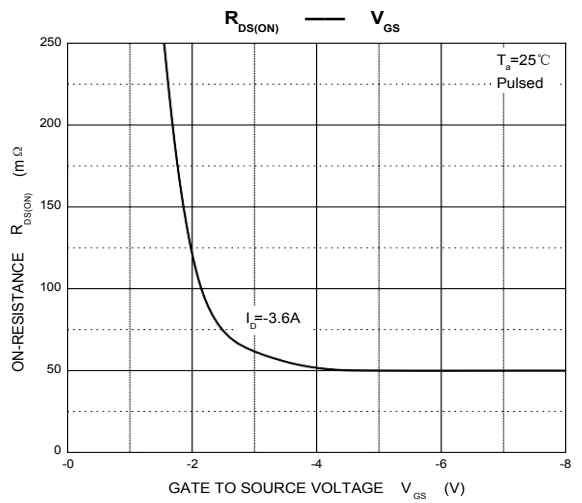
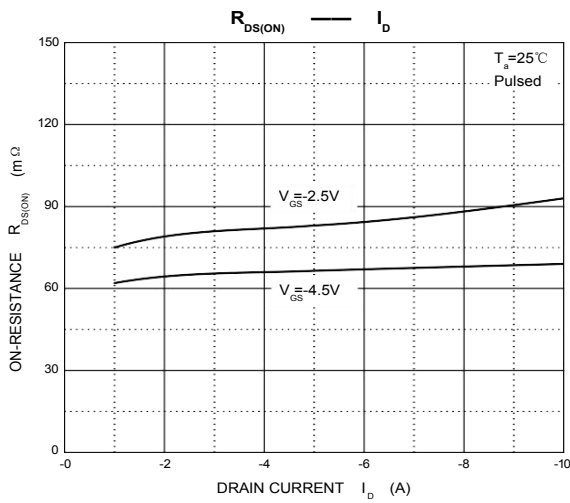
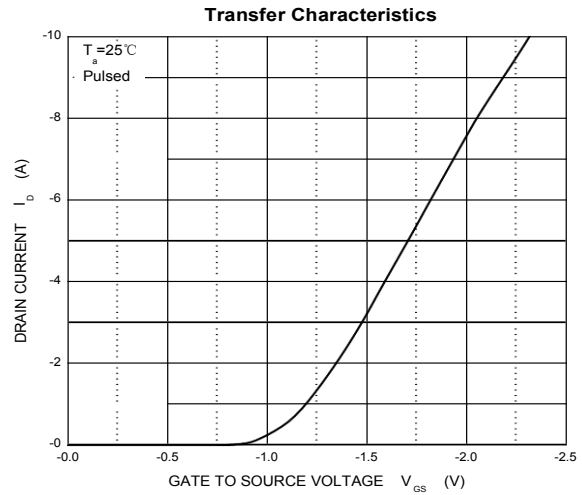
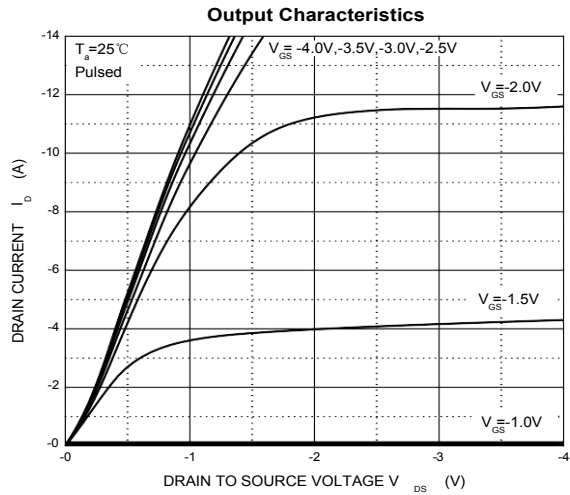


$R_{DS(ON)}$ — V_{GS}

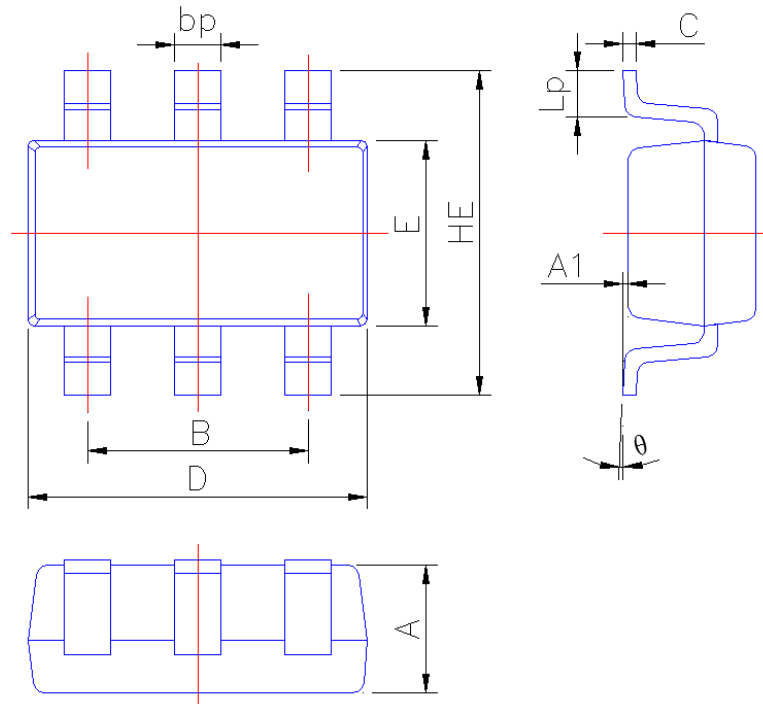


Typical Characteristics

P-Channel MOS



SOT-23-6L-Package Outline Dimensions



Symbol	Dimension in Millimeters	
	Min	Max
A	1.05	1.20
A1	0.010	0.100
B	1.80	2.00
bp	0.35	0.50
C	0.09	0.15
D	2.80	3.00
E	1.50	1.70
HE	2.60	3.00
Lp	0.25	0.55
θ	2°	6°